



MMD Adds New Process Capabilities for MEMS

Cost-Effective Offerings in Flexible Substrates, Exotic Evaporation, & Thru-Silicon Vias

For Immediate Release

(Toledo, OH) Officials at Midwest MicroDevices today announced that the wafer fab has expanded its menu of processes to include special capabilities not broadly available at very high-volume foundries that target mass market consumer applications. These offerings are a direct result of MMD's continuous search for methods to improve costs and yields for its customers.

First, MMD has developed a means of processing flexible substrates using its standard MEMS processing equipment without incurring substantial special tooling charges. Such capabilities here-to-fore demanded unusual processing which both increased costs and lowered yields. MMD's approach is valid for many flexible materials and enables standard fabrication methods with yields comparable to those achieved with standard silicon wafer processing.

Next, MMD announces it has installed a thermal evaporation system coupled to its e-beam evaporation system. This new capability allows evaporation of exotic materials increasingly being deployed in specialized MEMS applications such as *Antimony, Bismuth, Silicon Monoxide*, and other materials. The expanded capability enables MMD to evaporate multiple layers of any combination of typical metals and exotic materials without breaking vacuum.

Finally, MMD announces that it has recently completed a proof-of-principle fab run with *Thru-Silicon Vias* (TSVs). MMD has been performing research on a more cost-effective method of creating TSVs, culminating in recent fab work to validate through-wafer connectivity using polysilicon for conduction. MMD is seeking customers and developmental partners to continue this work and extend it to metalized TSVs more suitable for RF applications.

MMD has multiple specialized MEMS devices in recurring production. The strong customer interest in MMD lies in its cost-effective approach to MEMS wafer fabrication during early stages of development, pre-production, and production of wafers. MMD has no minimum order requirements and uses a flexible engagement model. Products fabricated to date include thermal sensors, pressure sensors, biomedical devices, RF, and some non-MEMS thin film devices.

About Midwest MicroDevices

Based in Ohio, Midwest MicroDevices is a dedicated wafer foundry providing thin-film fabrication services for external customers in both MEMS and non-MEMS applications. As a focused wafer foundry, MMD offers no products of its own which provides assurance that a customer's intellectual property remains 100% protected. MMD targets customers in emerging and volume applications for *Instrumentation, Telecom, Life Sciences, & Aerospace/Defense*.

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